

Series HXP-600

600 W Power Resistor at 85°C bottom case

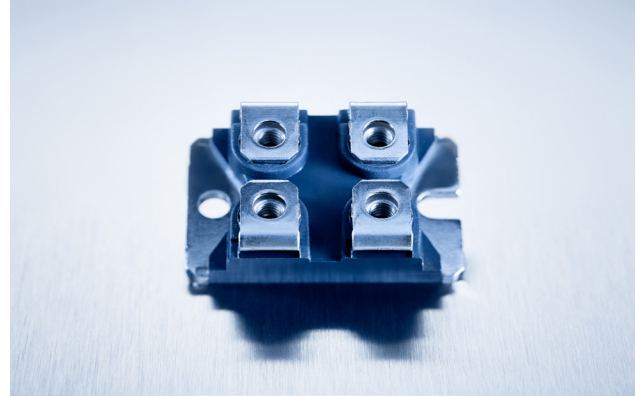
A Miba Group Company

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Due to our Non-Inductive design, the HXP series is ideally suited for high-frequency and pulse-loading applications. Through direct mounting on a heat sink, significant cost advantage can be realized. Main applications are: variable speed drives, power supplies, control devices, telecommunications, robotics, motor controls and other switching devices.

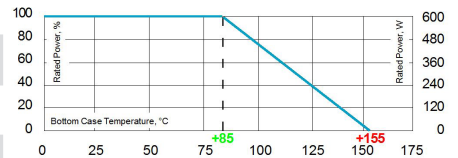
Features

- multiple resistors in 1 package
- Non-Inductive design
- ROHS compliant
- Materials in accordance with UL 94 V-0
- General pulse load information (ask for details)



Technical Specifications

Resistance value	0.15 Ω ≤ 5 KΩ (higher values on special request)
Resistance tolerance	±5 % to 10 % (configuration 4,5,6 only tolerance ±10% possible)
Temperature coefficient	> 1R: ±150 ppm/°C (at +85°C ref. to +25°C) lower TCR on special request for limited ohmic values
Power rating	up to 600 W at 85°C bottom case temperature (see configurations)
Short time overload	1.25x rated power at 85°C bottom case temperature for 10 sec., ΔR = 0.4% max. (for conf. 1, 2 and 3)
Maximum working voltage	1,000 V DC (up to 2,000 V on special request = "S"-version)
Partial discharge	up to 2,000 V on 80pC (Tests only on special request)
Voltage proof	dielectric strength up to 4,000 V DC against ground
Insulation resistance	> 10 GΩ at 1,000 V DC
Isolation voltage between R1 & R2 & R3	500 V DC (1,000 V DC on special request)
Protection class	acc. to IEC 950/CSA22.2 950/M-89 and EN 60950.88:2
Comparative Tracking Index (CTI)	standard 500 V
Heat resistance to cooling plate	Rth < 0.12 K/W
Capacitance/mass	45 pF (typical), measuring frequency 10 kHz
Serial inductivity	HXP-1 typical 40 nH, measuring frequency 10 kHz
Working temperature range	-55°C to +155°C
Mounting - torque for base plate (static)	1.3 Nm to 1.5 Nm M4 screws
Mounting - torque for contacts (static)	1.1 Nm to 1.3 Nm M4 screws, screw-in depth max. 5mm
Weight	~27 g



Derating (thermal resist.) HXP-600:
8.33 W/K (0.12 K/W) (for conf. 1, 2 and 3)

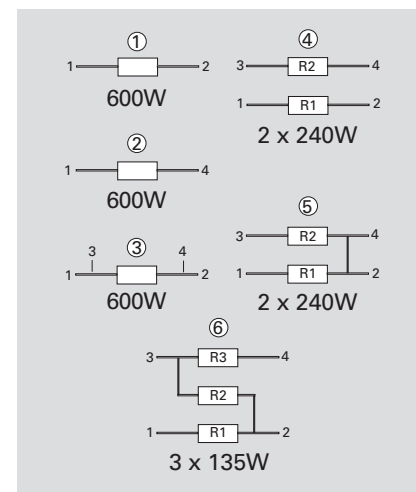
Best results can be reached by using a thermal transfer compound with a heat conductivity of at least 2.9 W/mK. The flatness of the cooling plate must be better than 0.05 mm overall. Surface roughness should not exceed 6.4 μm.

How to make an order

HXP-600-Configuration_Ohmic Value_Tolerance

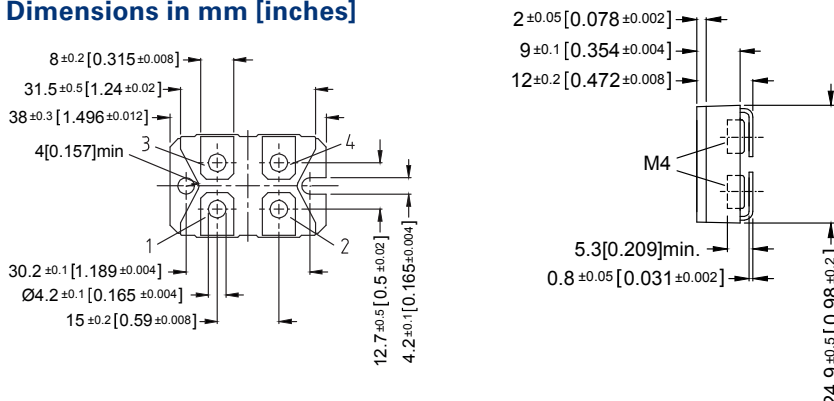
For example:
HXP-600-1 27R 10% or
HXP-600-4 2x220R 5%

Configurations (P / package)



Version 5: ohmic value between contact 2 and 4 = 3mΩ

Dimensions in mm [inches]



The above spec. sheet features our standard products. For further options please contact our local EBG representative or contact us directly.